| Parameters | Ratings | Units |
| :--- | :---: | :---: |
| Blocking Voltage | 600 | $\mathrm{~V}_{\mathrm{P}}$ |
| Load Current | 130 | $\mathrm{~mA}_{\mathrm{rms}} / \mathrm{mA}_{\mathrm{DC}}$ |
| On-Resistance (max) | 35 | $\Omega$ |

## Features

- $5000 \mathrm{~V}_{\text {rms }}$ Input/Output Isolation
- Low Drive Power Requirements
- High Reliability
- Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- Small 6-Pin Package
- Flammability Rating UL 94 V-0


## Applications

- Sensor Circuitry
- Instrumentation
- Multiplexers
- Data Acquisition
- Electronic Switching
- I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment: Patient/Equipment Isolation
- Aerospace
- Industrial Controls


## Description

The PLA194 is a single-pole, normally open (1-Form-A) solid state relay that uses optically coupled relay technology to provide an enhanced $5000 \mathrm{~V}_{\mathrm{rms}}$ isolation barrier between the input and the output of the relay.
Its optically coupled outputs, which use the patented OptoMOS architecture, are controlled by a highly efficient infrared LED.

## Approvals

- UL-Recognized Component: File Number E76270
- CSA Certified Component: Certificate 1117539
- EN/IEC 60950-1 Certified Component: Certificate available on our website


## Ordering Information

| Part \# | Description |
| :--- | :--- |
| PLA194 | 6-Pin DIP (50/Tube) |
| PLA194S | 6-Pin Surface Mount (50/Tube) |
| PLA194STR | 6-Pin Surface Mount (1000/Reel) |

## Pin Configuration



DC-Only Configuration


Switching Characteristics of Normally Open Devices


Absolute Maximum Ratings @ $25^{\circ} \mathrm{C}$

| Parameter | Min | Max | Units |
| :--- | :---: | :---: | :---: |
| Blocking Voltage | - | 600 | $\mathrm{~V}_{\mathrm{p}}$ |
| Reverse Input Voltage | - | 5 | V |
| Input Control Current | - | 50 | mA |
| Peak (10ms) | - | 1 | A |
| Input Power Dissipation ${ }^{1}$ | - | 150 | mW |
| Total Package Dissipation ${ }^{2}$ | - | 800 | mW |
| ESD Rating, Human Body Model | 8 | - | kV |
| Isolation Voltage, Input to Output | 5000 | - | $\mathrm{V}_{\text {rms }}$ |
| Operational Temperature | -40 | 85 | ${ }^{\circ} \mathrm{C}$ |
| Storage Temperature | -40 | 125 | ${ }^{\circ} \mathrm{C}$ |

${ }^{1}$ Derate linearly $1.33 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$
${ }^{2}$ Derate linearly $6.67 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at $+25^{\circ} \mathrm{C}$, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

Electrical Characteristics @ $25^{\circ} \mathrm{C}$

| Parameters | Conditions | Symbol | Min | Typ | Max | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Output Characteristics |  |  |  |  |  |  |
| Load Current ${ }^{1}$ <br> Continuous, AC/DC Configuration | - | $\mathrm{I}_{\mathrm{L}}$ | - | - | 130 | $m A_{\text {rms }} / \mathrm{mA}_{\text {DC }}$ |
| Continuous, DC-Only Configuration | - |  | - | - | 200 | $m A_{D C}$ |
| Peak | $\mathrm{t}=10 \mathrm{~ms}$ | ILPK | - | - | $\pm 400$ | $\mathrm{mA}_{\mathrm{p}}$ |
| On-Resistance ${ }^{2}$ |  | $\mathrm{R}_{\mathrm{ON}}$ |  |  |  | $\Omega$ |
| AC/DC Configuration | $\mathrm{I}_{\mathrm{L}}=130 \mathrm{~mA}$ |  | - | 26 | 35 |  |
| DC-Only Configuration | $\mathrm{I}_{\mathrm{L}}=200 \mathrm{~mA}$ |  | - | - | 18 |  |
| Off-State Leakage Current | $\mathrm{V}_{\mathrm{L}}=600 \mathrm{~V}_{\mathrm{P}}$ | $\mathrm{I}_{\text {LEAK }}$ | - | - | 1 | $\mu \mathrm{A}$ |
| Switching Speeds | $\mathrm{I}_{\mathrm{F}}=5 \mathrm{~mA}, \mathrm{~V}_{\mathrm{L}}=10 \mathrm{~V}$ |  |  |  |  | ms |
| Turn-On |  | $t_{\text {on }}$ | - | 0.85 | 3 |  |
| Turn-Off |  | $\mathrm{t}_{\text {off }}$ | - | 0.46 | 2 |  |
| Output Capacitance | $\mathrm{I}_{\mathrm{F}}=0 \mathrm{~mA}, \mathrm{~V}_{\mathrm{L}}=50 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}$ | $\mathrm{C}_{\text {OUT }}$ | - | 5 | - | pF |
| Input Characteristics |  |  |  |  |  |  |
| Input Control Current to Activate ${ }^{3}$ | $\mathrm{I}_{\mathrm{L}}=130 \mathrm{~mA}$ | $I_{\text {F }}$ | - | 0.44 | 2 | mA |
| Input Control Current to Deactivate | - | $I_{F}$ | 0.1 | - | - | mA |
| Input Voltage Drop | $\mathrm{I}_{\mathrm{F}}=5 \mathrm{~mA}$ | $V_{F}$ | 0.9 | 1.2 | 1.5 | V |
| Reverse Input Current | $\mathrm{V}_{\mathrm{R}}=5 \mathrm{~V}$ | $I_{R}$ | - | - | 10 | $\mu \mathrm{A}$ |
| Common Characteristics |  |  |  |  |  |  |
| Input to Output Capacitance | $\mathrm{V}_{10}=0 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}$ | $\mathrm{C}_{10}$ | - | 3 | - | pF |

${ }^{1}$ Load current derates linearly from $130 \mathrm{~mA} @ 25^{\circ} \mathrm{C}$ to $65 \mathrm{~mA} @ 85^{\circ} \mathrm{C}$.
${ }^{2}$ Measurement taken within 1 second of on-time.
${ }^{3}$ For applications requiring high temperature operation (greater than $60^{\circ} \mathrm{C}$ ), a minimum LED drive current of 3 mA is recommended.

## PERFORMANCE DATA*


*Unless otherwise noted, data presented in these graphs is typical of device operation at $25^{\circ} \mathrm{C}$
For guaranteed parameters not indicated in the written specifications, please contact our application department.

## PERFORMANCE DATA*



## Output Capacitance vs. Load Voltage




## Manufacturing Information

## Moisture Sensitivity

©
All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, IPC/JEDEC J-STD-020, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a Moisture Sensitivity Level (MSL) classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard IPC/JEDEC J-STD-033.

| Device | Moisture Sensitivity Level (MSL) Classification |
| :---: | :---: |
| PLA194 / PLA194S | MSL 1 |

## ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

## Soldering Profile

Provided in the table below is the Classification Temperature $\left(T_{C}\right)$ of this product and the maximum dwell time the body temperature of this device may be $\left(T_{C}-5\right)^{\circ} \mathrm{C}$ or greater. The classification temperature sets the Maximum Body Temperature allowed for this device during lead-free reflow processes. For through-hole devices, and any other processes, the guidelines of J-STD-020 must be observed.

| Device | Classification Temperature ( $\mathrm{T}_{\mathrm{c}}$ ) | Dwell Time $\left(\mathrm{t}_{\mathrm{p}}\right)$ | Max Reflow Cycles |
| :---: | :---: | :---: | :---: |
| PLA194 | $250^{\circ} \mathrm{C}$ | 30 seconds | 1 |
| PLA194S | $250^{\circ} \mathrm{C}$ | 30 seconds | 3 |

## Board Wash

IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include, but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to flux or solvents that are Chlorine- or Fluorine-based.

RoHS e3

## PLA194



## PLA194S



PCB Land Pattern


## PLA194STR Tape \& Reel



NOTES:

1. All dimensions carry tolerances of EIA Standard 481-2
. The tape complies with all "Notes" for constant dimensions listed on page 5 of EIA-481-2

For additional information please visit our website at: www.ixysic.com
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[^0]:    Specification: DS-PLA194-R03
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